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## **DIODES, SWITCHING,**

## **BASED ON TYPE 1N4153**

## ESCC Detail Specification No. 5101/016

ISSUE 1 October 2002



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## **DIODES, SWITCHING,**

## BASED ON TYPE 1N4153

## **ESA/SCC** Detail Specification No. 5101/016



# space components coordination group

		Appro	oved by
lssue/Rev.	Date	SCCG Chairman	ESA Director General or his Deputy
Issue 2	February 1992	Tomores	J. tak
Revision 'A'	November 1995	Tomomens	Hoom



ISSUE 2

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## **DOCUMENTATION CHANGE NOTICE**

Rev. Letter	Rev. Date	Reference	CHANGE Item	Approved DCR No.
		following DCR's:- Cover Page DCN Para. 1.4 Table 1(a) Table 1(b) Para. 2 Para. 4.2.2 Para. 4.2.3 Para. 4.2.4 Para. 4.2.4 Para. 4.7.1 Table 2 D.C. Table 2 A.C. Table 3 Figure 4 Table 4 Figure 5 Para. 4.8.1	<ul> <li>No. 4, symbol corrected</li> <li>Reference to ESA/SCC Basic Specification No. 23500 added</li> <li>PIND deviation entry standardised</li> <li>Reference to Radiographic Inspection deleted</li> <li>Title corrected</li> <li>Last sentence standardised</li> <li>Format and sequence standardised</li> <li>Title and format standardised</li> <li>Format standardised</li> <li>Format standardised</li> </ul>	None None 23476 21021 23476 21025 21043 21049 23476 23476 23476 23476 23476 23476 23476 23476 23476 23476 23476 23476 23476 23476
'A'	Nov. '95	P1. Cover page P2. DCN P3. T of C P5. Para. 1.7	: New Para 1.7 entry added : New Para. 1.7 entry added	None None 21083 21083

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## APPENDICES (Applicable to specific Manufacturers only)

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#### 1. <u>GENERAL</u>

#### 1.1 <u>SCOPE</u>

This specification details the ratings, physical and electrical characteristics, test and inspection data for Diodes, Switching, based on Type 1N4153. It shall be read in conjunction with ESA/SCC Generic Specification No. 5000, the requirements of which are supplemented herein.

#### 1.2 COMPONENT TYPE VARIANTS

Variants of the basic type diodes specified herein, which are also covered by this specification, are given in Table 1(a).

#### 1.3 MAXIMUM RATINGS

The maximum ratings, which shall not be exceeded at any time during use or storage, applicable to the diodes specified herein, are as scheduled in Table 1(b).

#### 1.4 PARAMETER DERATING INFORMATION

The parameter derating information applicable to the diodes specified herein, is shown in Figure 1.

#### 1.5 PHYSICAL DIMENSIONS

The physical dimensions of the diodes specified herein, are shown in Figure 2.

#### 1.6 FUNCTIONAL DIAGRAM

The functional diagram, showing lead identification, of the diodes specified herein, is shown in Figure 3.

### 1.7 HIGH TEMPERATURE TEST PRECAUTIONS

For tin-lead plated or solder-dipped lead finish, all tests to be performed at a temperature that exceeds +125°C shall be carried out in 100% inert atmosphere.



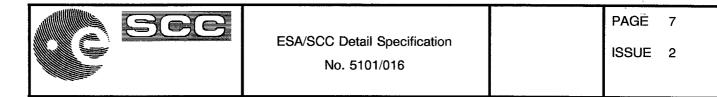
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## TABLE 1(a) - TYPE VARIANTS

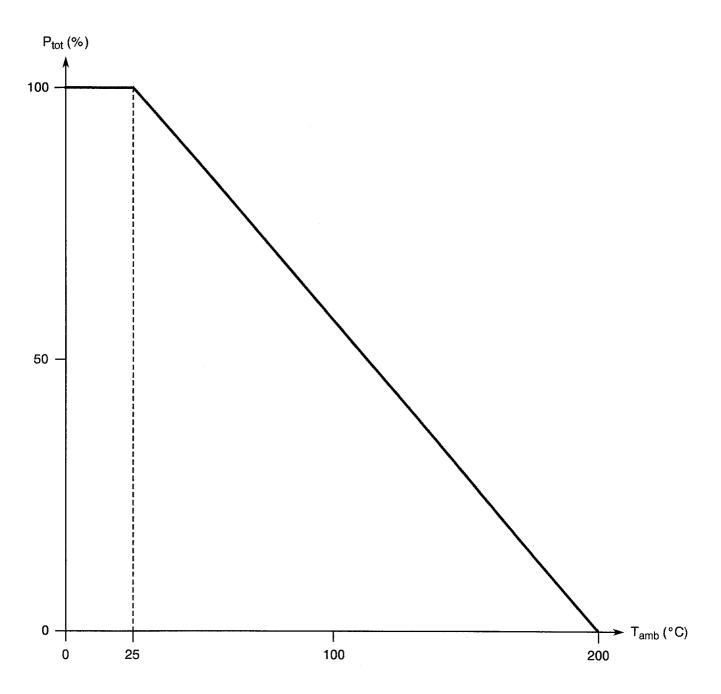
VARIANT	CASE	LEAD MATERIAL AND/OR FINISH
01	D035	C3 or C4

## TABLE 1(b) - MAXIMUM RATINGS

No.	CHARACTERISTICS	SYMBOL	MAXIMUM RATING	UNIT	REMARKS
1	DC Reverse Voltage	V <sub>R</sub>	-50	V	
2	Peak Reverse Voltage	V <sub>RM</sub>	75	V	
3	Total Power Dissipation	P <sub>tot</sub>	400	mW	
4	Operating Temperature Range	T <sub>op</sub>	-55 to +200	°C	T <sub>amb</sub>
5	Storage Temperature Range	T <sub>stg</sub>	-65 to +250	°C	
6	Soldering Temperature	T <sub>sol</sub>	+ 260	°C	Time: ≤10s; Distance from case: ≥1.5mm



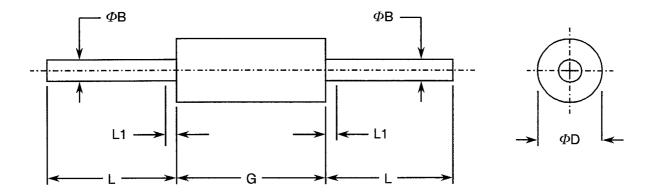
## FIGURE 1 - PARAMETER DERATING INFORMATION



Power Dissipation versus Temperature



#### FIGURE 2 - PHYSICAL DIMENSIONS



SYMBOL	MILLIM	ETRES	NOTES
STMBOL	MIN.	MAX.	NOTES
ΦB	0.458	0.558	-
ΦD	1.42	1.91	1
G	3.56	4.57	1
L	12.70	-	-
L1	-	1.27	2

#### **NOTES**

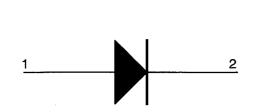
- 1. Package contour optional within cylinder of diameter  $\Phi D$  and length G. Slugs, if any, shall be included within this cylinder but shall not be subject to the minimum limit of  $\Phi D$ .
- 2. Lead diameter not controlled in this zone to allow for flash, lead finish build-up, and minor irregularities other than slugs.

#### **FIGURE 3 - FUNCTIONAL DIAGRAM**

Anode

Cathode

1 2



#### **NOTES**

1. The cathode end shall be marked with a coloured ring.



#### 2. APPLICABLE DOCUMENTS

The following documents form part of this specification and shall be read in conjunction with it:-

- (a) ESA/SCC Generic Specification No. 5000 for Discrete Semiconductors.
- (b) MIL-STD-750, Test Methods and Procedures for Semiconductor Devices.
- (c) ESA/SCC Basic Specification No. 23500, Requirements for Lead Materials and Finishes for Space Application.

#### 3. TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESA/SCC Basic Specification No. 21300 shall apply.

#### 4. **REQUIREMENTS**

4.1 <u>GENERAL</u>

The complete requirements for procurement of the diodes specified herein shall be as stated in this specification and ESA/SCC Generic Specification No. 5000 for Discrete Semiconductors. Deviations from the Generic Specification, applicable to this Detail Specification only, are listed in Para. 4.2.

Deviations from the applicable Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalent to the ESA/SCC requirements and do not affect the components' reliability, are listed in the appendices attached to this specification.

#### 4.2 DEVIATIONS FROM GENERIC SPECIFICATION

- 4.2.1 <u>Deviations from Special In-process Controls</u> None.
- 4.2.2 Deviations from Final Production Tests (Chart II)
  - (a) Para. 9.2.1, Bond Strength Test: Not applicable.
  - (b) Para. 9.2.2, Die Shear Test: Not applicable.
  - (b) Para. 9.7, Particle Impact Noise Detection (PIND) Test: Not applicable.
- 4.2.3 <u>Deviations from Burn-in and Electrical Measurements (Chart III)</u>(a) Para 7.1.1(a), H.T.R.B. Test: Not applicable.
- 4.2.4 Deviations from Qualification Tests (Chart IV)
  - (a) Para. 9.2.3, Bond Strength Test: Not applicable.
  - (b) Para. 9.2.4, Die Shear Test: Not applicable.
- 4.2.5 Deviations from Lot Acceptance Tests (Chart V) None.



#### 4.3 MECHANICAL REQUIREMENTS

#### 4.3.1 Dimension Check

The dimensions of the diodes specified herein shall be checked. They shall conform to those shown in Figure 2.

#### 4.3.2 Weight

The maximum weight of the diodes specified herein shall be 0.2 grammes.

#### 4.3.3 Terminal Strength

The requirements for terminal strength testing are specified in Section 9 of ESA/SCC Generic Specification No. 5000. The test conditions shall be as follows:-

Test Condition : 'A'.

Applied Force : 5.0 Newtons.

Duration : 10 seconds.

#### 4.4 MATERIALS AND FINISHES

The materials and finishes shall be as specified herein. Where a definite material is not specified, a material which will enable the diodes specified herein to meet the performance requirements of this specification shall be used. Acceptance or approval of any constituent material does not guarantee acceptance of the finished product.

#### 4.4.1 <u>Case</u>

Glass, hermetically sealed.

#### 4.4.2 Lead Material and Finish

The lead material shall be Type 'C' with Type '3' or Type '4' finish in accordance with the requirements of ESA/SCC Basic Specification No. 23500.

#### 4.5 MARKING

#### 4.5.1 General

The marking of all components delivered to this specification shall be in accordance with the requirements of ESA/SCC Basic Specification No. 21700. Each component shall be marked in respect of:-

- (a) Lead Identification.
- (b) The SCC Component Number.
- (c) Traceability Information.

#### 4.5.2 Lead Identification

Lead identification shall be as shown in Figures 2 and 3.



#### 4.5.3 The SCC Component Number

Each component shall bear the SCC Component Number which shall be constituted and marked as follows:

	510101601B	•
Detail Specification Number		
Type Variant (see Table 1(a))		
Testing Level (B or C, as applicable) -		

#### 4.5.4 Traceability Information

Each component shall be marked in respect of traceability information as defined in ESA/SCC Basic Specification No. 21700.

#### 4.5.5 Marking of Small Components

When it is considered that the component is too small to accommodate the marking as specified above, as much as space permits shall be marked. The order of precedence shall be as follows:-

- (a) Lead identification.
- (b) The SCC Component number.
- (c) Traceability information.

The marking information in full shall accompany each component in its primary package.

#### 4.6 ELECTRICAL MEASUREMENTS

#### 4.6.1 Electrical Measurements at Room Temperature

The parameters to be measured at room temperature are scheduled in Table 2. The measurements shall be performed at  $T_{amb}$  = + 22 ± 3 °C.

#### 4.6.2 <u>Electrical Measurements at High and Low Temperatures</u>

The parameters to be measured at high and low temperatures are scheduled in Table 3.

#### 4.6.3 Circuits for Electrical Measurements

Circuits for use in performing electrical measurements listed in Tables 2 and 3 are shown in Figure 4.

#### 4.7 BURN-IN TESTS

#### 4.7.1 Parameter Drift Values

The parameter drift values applicable to burn-in are specified in Table 4 of this specification. Unless otherwise stated, measurements shall be performed at  $T_{amb} = +22 \pm 3$  °C. The parameter drift values ( $\Delta$ ) applicable to the scheduled parameters shall not be exceeded. In addition to these drift value requirements for a given parameter, the appropriate limit value specified in Table 2 shall not be exceeded.

#### 4.7.2 Conditions for Burn-in

The requirements for Burn-in are specified in Section 7 of ESA/SCC Generic Specification No. 5000. The conditions for Burn-in shall be as specified in Table 5 of this specification.

#### 4.7.3 Electrical Circuits for Burn-in

Circuits for use in performing the Burn-in tests are shown in Figure 5 of this specification.



## TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - D.C. PARAMETERS

No.	CHARACTERISTICS	SYMBOL	MIL-STD-750	TEST	LIM	ITS	UNIT
110.	UNARO LENGTOS	STMDOL	TEST METHOD	CONDITIONS	MIN.	MAX.	UNIT
1	DC Forward Voltage	V <sub>F</sub>	4011	I <sub>F</sub> =20mA	0.74	0.88	V
2	DC Reverse Current	۱ <sub>R</sub>	4016	V <sub>R</sub> = -50V	-	0.05	μA
3	DC Breakdown Reverse Voltage	V <sub>(BR)</sub>	4021	I <sub>R</sub> =5.0µА	75	-	V

#### TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - A.C. PARAMETERS

No.	CHARACTERISTICS	SYMBOL	MIL-STD-750	TEST	LIM	ITS	UNIT
110.	UNAROTERISTICS	OTMBOL	TEST METHOD	CONDITIONS	MIN.	MAX.	UNIT
1	Capacitance	С	4001	V <sub>R</sub> = 0 f = 1.0MHz	-	2.0	pF
2	Reverse Current Recovery Time	t <sub>rr</sub>	4031, Condition 'B'	$I_F = -I_{RM} = 10mA$ $i_{rr} = 1.0mA$	-	4.0	ns

#### **NOTES**

1. Measurements shall be performed on a sample basis, LTPD7.



## TABLE 3 - ELECTRICAL MEASUREMENTS AT HIGH AND LOW TEMPERATURES

No.	CHARACTERISTICS	SYMBOL	MIL-STD-750	TEST	LIM	ITS	UNIT
NO.	CHARACTERISTICS	STNBOL	TEST METHOD	CONDITIONS	MIN.	MAX.	UNIT
2	DC Reverse Current	I <sub>R</sub>	4016	$T_{amb}$ = +150°C V <sub>R</sub> = -50V	-	0.05	mA

#### FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS

Not applicable

#### TABLE 4 - PARAMETER DRIFT VALUES

No.	CHARACTERISTICS			CHANGE LIMITS	UNIT	
1	DC Forward Voltage	V <sub>F</sub>	As per Table 2	As per Table 2	± 100	mV
2	DC Reverse Current	I <sub>R</sub>	As per Table 2 As per Table 2		± 100 or (1) ±5.0	% nA

#### <u>NOTES</u>

1. Whichever is the greater.



## TABLE 5 - CONDITIONS FOR BURN-IN AND OPERATING LIFE TEST

No.	CHARACTERISTICS	SYMBOL	CONDITION	UNIT
1	Working Voltage	V <sub>WK</sub>	50V(PK)	V
2	Average Rectified Current	lo	150	mA
3	Frequency	f	50 to 60	Hz

## FIGURE 5 - ELECTRICAL CIRCUIT FOR BURN-IN AND OPERATING LIFE TEST

Not applicable.



#### 4.8 <u>ENVIRONMENTAL AND ENDURANCE TESTS (CHARTS IV AND V OF ESA/SCC GENERIC</u> SPECIFICATION NO. 5000)

#### 4.8.1 Electrical Measurements on Completion of Environmental Tests

The parameters to be measured on completion of environmental tests are scheduled in Table 2. Unless otherwise stated, the measurements shall be performed at  $T_{amb}$  = +22±3°C.

#### 4.8.2 Electrical Measurements at Intermediate Points and on Completion of Endurance Tests

The parameters to be measured at intermediate points and on completion of endurance tests are scheduled in Table 6. Unless otherwise stated, the measurements shall be performed at  $T_{amb}$  = +22 ± 3 °C.

#### 4.8.3 Conditions for Operating Life Tests (Part of Endurance Testing)

The requirements for operating life testing are specified in Section 9 of ESA/SCC Generic Specification No. 5000. The conditions for operating life testing shall be the same as specified in Table 5 for the burn-in test.

#### 4.8.4 Electrical Circuits for Operating Life Tests

Not applicable.

#### 4.8.5 Conditions for High Temperature Storage Test (Part of Endurance Testing)

The requirements for the high temperature storage test are specified in ESA/SCC Generic Specification No. 5000. The temperature to be applied shall be the maximum storage temperature specified in Table 1(b) of this specification.



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## TABLE 6 - ELECTRICAL MEASUREMENTS AT INTERMEDIATE POINTS AND ON COMPLETION OF ENDURANCE TESTS

No.	CHARACTERISTICS	SYMBOL	SPEC. AND/OR TEST METHOD	TEST CONDITIONS	LIMITS		
					MIN.	MAX.	UNIT
1	DC Forward Voltage	V <sub>F</sub>	As per Table 2	As per Table 2	-	0.88	V
2	DC Reverse Current	I <sub>R</sub>	As per Table 2	As per Table 2	-	50	μA



## APPENDIX 'A'

Page 1 of 1

## AGREED DEVIATIONS FOR UNITRODE (USA)

ITEMS AFFECTED	DESCRIPTION OF DEVIATIONS		
Para. 4.2.2 Para. 4.2.4	Internal (pre-encapsulation) Visual Inspection may be performed to MIL-STD-750, Test Method 2074.		
Para. 4.2.2 Para. 4.2.3 Para. 4.2.4 Para. 4.2.5	External Visual Inspection may be performed to MIL-STD-750, Test Method 2071.		
Para. 4.2.3	Radiographic Inspection may be performed to MIL-STD-750, Test Method 2076.		